

Title (en)

PLASMA ETCHED CATALYTIC LAMINATE WITH TRACES AND VIAS

Title (de)

PLASMAGEÄTZTES KATALYTISCHES LAMINAT MIT LEITERBAHNEN UND DURCHKONTAKTIERUNGEN

Title (fr)

STRATIFIÉ CATALYTIQUE GRAVÉ AU PLASMA À TRACES ET TROUS D'INTERCONNEXION

Publication

EP 3501242 A1 20190626 (EN)

Application

EP 17842034 A 20170816

Priority

- US 201615240133 A 20160818
- US 201715645957 A 20170710
- US 2017047062 W 20170816

Abstract (en)

[origin: WO2018035184A1] A circuit board is formed from a catalytic laminate having a resin rich surface with catalytic particles dispersed below a surface exclusion depth. The catalytic laminate is subjected to a drilling and blanket surface plasma etch operation to expose the catalytic particles, followed by an electroless plating operation which deposits a thin layer of conductive material on the surface. A photo-masking step follows to define circuit traces, after which an electro-plating deposition occurs, followed by a resist strip operation and a quick etch to remove electroless copper which was previously covered by photoresist.

IPC 8 full level

H05K 1/11 (2006.01); **H05K 1/09** (2006.01); **H05K 3/46** (2006.01)

CPC (source: CN EP KR)

H05K 1/02 (2013.01 - CN); **H05K 1/03** (2013.01 - CN); **H05K 1/0313** (2013.01 - CN); **H05K 3/0011** (2013.01 - CN); **H05K 3/108** (2013.01 - CN); **H05K 3/185** (2013.01 - CN EP KR); **H05K 3/422** (2013.01 - CN EP KR); **H05K 3/426** (2013.01 - CN EP KR); **H05K 3/108** (2013.01 - EP KR); **H05K 2201/0236** (2013.01 - CN EP KR); **H05K 2201/0344** (2013.01 - CN EP KR); **H05K 2201/0376** (2013.01 - CN EP KR); **H05K 2203/025** (2013.01 - CN EP KR); **H05K 2203/095** (2013.01 - CN EP KR); **H05K 2203/107** (2013.01 - CN EP KR)

Cited by

EP3539362A4

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2018035184 A1 20180222; CN 109906670 A 20190618; CN 114501781 A 20220513; EP 3501242 A1 20190626; EP 3501242 A4 20200415; KR 102649271 B1 20240318; KR 20190049736 A 20190509; KR 20220070580 A 20220531

DOCDB simple family (application)

US 2017047062 W 20170816; CN 201780064641 A 20170816; CN 202210060248 A 20170816; EP 17842034 A 20170816; KR 20197007725 A 20170816; KR 20227017285 A 20170816